

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YI-PAI CHU	05/11/2018
LIANG-CHUN MA	05/14/2018
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<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15980282
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<b>DATE SIGNED:</b>	05/15/2018
<b>Total Attachments: 3</b>	
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## ASSIGNMENT

WHEREAS, **YI-PAI CHU AND LIANG-CHUN MA**, hereinafter called the “inventors”, have made the invention described in the United States patent application entitled **“AIRFLOW SEALING BY FLEXIBLE RUBBER WITH I-BEAM AND HONEYCOMB STRUCTURE,”** Attorney Docket No. 102450.00490 (111255.01), for a full description of which reference is here made to an application for Letters Patent of the United States filed herewith; and

We hereby also sell, assign and transfer unto DELL PRODUCTS L.P., hereinafter called the “Assignee” having a place of business in One Dell Way, Round Rock, Texas, 78682 USA, the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and we further authorize DELL PRODUCTS L.P. to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation, continuation-in-part, or reissue, to DELL PRODUCTS L.P., for the sole use and benefit of DELL PRODUCTS L.P., its successors, assigns and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to DELL PRODUCTS L.P.

We agree that, when requested, we will, without charge to DELL PRODUCTS L.P., but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in DELL PRODUCTS L.P., its successors, assigns and legal representatives or nominees.

We covenant with DELL PRODUCTS L.P., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

NAME OF FIRST INVENTOR	YI-PAI CHU
SIGNATURE OF FIRST INVENTOR	<u>朱白 Yi-Pai Chu</u>
DATE	<u>2018/5/11</u>

NAME OF SECOND INVENTOR	LIANG-CHUN MA
SIGNATURE OF SECOND INVENTOR	馬良駿 Liang-Chun, Ma
DATE	2018/05/14